Product data sheet

# 1. General description

Planar Schottky barrier rectifier encapsulated in a CFP3-HP (SOD123HP) power flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Low forward voltage
- Low leakage current
- · High surge current robustness
- High power capability due to clip bond package
- · Power flat lead plastic package with exposed heatsink for optimal thermal connection
- Qualified according to AEC-Q101 and recommended for use in automotive applications

# 3. Applications

- Low voltage rectification
- · High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- · Reverse polarity protection
- · Low power consumption applications

## 4. Quick reference data

Table 1. Quick reference data

| Symbol             | Parameter               | Conditions   |     | Min | Тур | Max | Unit |
|--------------------|-------------------------|--|-----|-----|-----|-----|------|
| I <sub>F(AV)</sub> | average forward current | $\delta$ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 167 °C |     | -   | -   | 2   | Α    |
| V <sub>R</sub>     | reverse voltage         | T <sub>j</sub> = 25 °C                                       |     | -   | -   | 60  | V    |
| V <sub>F</sub>     | forward voltage         | I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = 25 °C         | [1] | -   | 580 | 650 | mV   |
| I <sub>R</sub>     | reverse current         | V <sub>R</sub> = 60 V; pulsed; T <sub>j</sub> = 25 °C        | [1] | -   | 25  | 60  | μA   |
|                    |                         | $V_R$ = 60 V; pulsed; $T_j$ = 125 °C                         | [1] | -   | 10  | 50  | mA   |

[1] Very short pulse, in order to maintain a stable junction temperature.



# 5. Pinning information

#### **Table 2. Pinning information**

| Pin | Symbol | Description | Simplified outline | Graphic symbol             |
|-----|--------|-------------|--------------------|----------------------------|
| 1   | K      | cathode[1]  |                    |                            |
| 2   | А      | anode       | 25                 | K <del>∭</del> A<br>sym001 |
|     |        |             | CFP3-HP (SOD123HP) |                            |

[1] The marking bar indicates the cathode.

# 6. Ordering information

#### **Table 3. Ordering information**

| Type number   | Package |  |          |
|---------------|---------|--|----------|
|               | Name    | Description  | Version  |
| PMEG6020EXE-Q | CFP3-HP | Power plastic surface mounted package; 2 terminals; 2.80 mm × 1.80 mm × 0.90 mm body | SOD123HP |

# 7. Marking

#### **Table 4. Marking codes**

| Type number   | Marking code |
|---------------|--------------|
| PMEG6020EXE-Q | AJ           |

# 8. Limiting values

### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol             | Parameter                           | Conditions   |     | Min | Max  | Unit |
|--------------------|-------------------------------------|--|-----|-----|------|------|
| $V_R$              | reverse voltage                     | T <sub>j</sub> = 25 °C   |     | -   | 60   | V    |
| I <sub>F</sub>     | forward current                     | $\delta$ = 1; $T_{sp} \le 165 °C$                                      |     | -   | 2.8  | А    |
| I <sub>F(AV)</sub> | average forward current             | $\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> ≤ 167 °C      |     | -   | 2    | А    |
| I <sub>FSM</sub>   | non-repetitive peak forward current | $t_p = 8.3 \text{ ms}$ ; half sine wave; $T_{j(init)} = 25 \text{ °C}$ |     | -   | 50   | А    |
| P <sub>tot</sub>   | total power dissipation             | T <sub>amb</sub> ≤ 25 °C   | [1] | -   | 0.75 | W    |
|                    |                                     |  | [2] | -   | 1.3  | W    |
| Tj                 | junction temperature                |  |     | -   | 175  | °C   |
| T <sub>amb</sub>   | ambient temperature                 |  |     | -55 | 175  | °C   |
| T <sub>stg</sub>   | storage temperature                 |  |     | -65 | 175  | °C   |

<sup>[1]</sup> Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

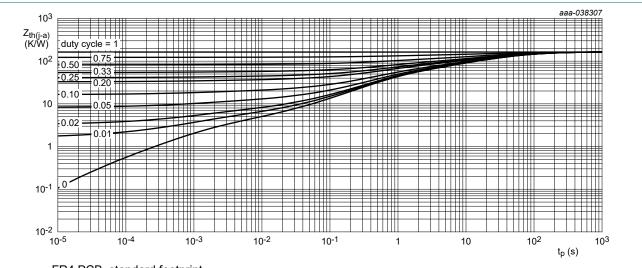
<sup>[2]</sup> Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

# 9. Thermal characteristics

**Table 6. Thermal characteristics** 

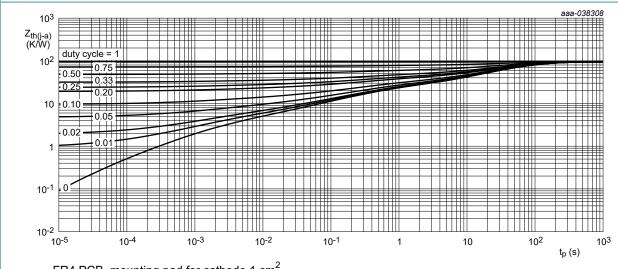
| Symbol               | Parameter  | Conditions  |         | Min | Тур | Max | Unit |
|----------------------|--|-------------|---------|-----|-----|-----|------|
| R <sub>th(j-a)</sub> | thermal resistance from                          | in free air | [1] [2] | -   | -   | 200 | K/W  |
| junction to ambie    | junction to ambient                              |             | [3] [2] | -   | -   | 115 | K/W  |
| $R_{th(j-sp)}$       | thermal resistance from junction to solder point |             | [4]     | -   | -   | 6   | K/W  |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

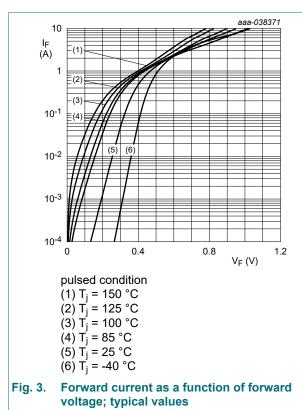
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

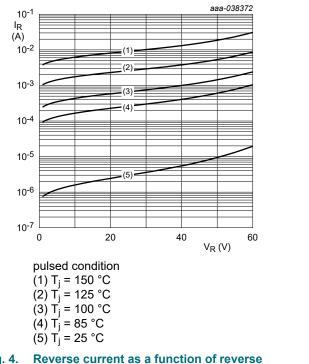
## 10. Characteristics

**Table 7. Characteristics** 

| Symbol          | Parameter                            | Conditions   |     | Min | Тур | Max | Unit |
|-----------------|--------------------------------------|--|-----|-----|-----|-----|------|
| $V_{(BR)R}$     | reverse breakdown voltage            | $I_R = 3 \text{ mA}$ ; pulsed; $T_j = 25 \text{ °C}$   | [1] | 60  | -   | -   | V    |
| V <sub>F</sub>  | forward voltage                      | I <sub>F</sub> = 1 A; pulsed; T <sub>j</sub> = 25 °C   | [1] | -   | 465 | 530 | mV   |
|                 |                                      | I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = 25 °C   | [1] | -   | 580 | 650 | mV   |
|                 |                                      | I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = -40 °C  | [1] | -   | 590 | 670 | mV   |
|                 |                                      | I <sub>F</sub> = 2 A; pulsed; T <sub>j</sub> = 125 °C  | [1] | -   | 540 | 630 | mV   |
| I <sub>R</sub>  | reverse current                      | V <sub>R</sub> = 60 V; pulsed; T <sub>j</sub> = 25 °C  | [1] | -   | 25  | 60  | μΑ   |
|                 |                                      | V <sub>R</sub> = 60 V; pulsed; T <sub>j</sub> = 125 °C   | [1] | -   | 10  | 50  | mA   |
| C <sub>d</sub>  | diode capacitance                    | V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>j</sub> = 25 °C  |     | -   | 100 | -   | pF   |
|                 |                                      | V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C   |     | -   | 36  | -   | pF   |
| t <sub>rr</sub> | reverse recovery time; step recovery | $I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$<br>$T_j = 25 \text{ °C}$      |     | -   | 4   | -   | ns   |
|                 | reverse recovery time; ramp recovery | $dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$<br>$T_j = 25 \text{ °C}$ |     | -   | 6   | -   | ns   |
| I <sub>RM</sub> | peak reverse recovery current        |  |     | -   | 0.6 | -   | Α    |
| Q <sub>rr</sub> | reverse recovery charge              |  |     | -   | 2.5 | -   | nC   |
| $V_{FRM}$       | peak forward recovery voltage        | $I_F = 0.5 \text{ A}$ ; $dI_F/dt = 20 \text{ A/}\mu\text{s}$ ; $T_j = 25 \text{ °C}$                   |     | -   | 420 | -   | mV   |

[1] Very short pulse, in order to maintain a stable junction temperature.





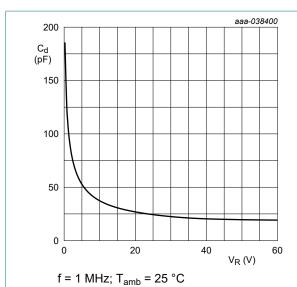
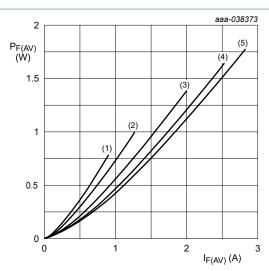
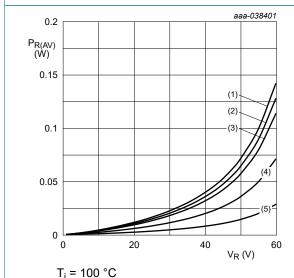


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



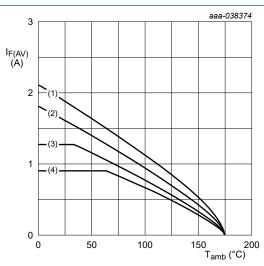
 $T_j = 100 \,^{\circ}\text{C}$ (1)  $\delta = 0.1$ (2)  $\delta = 0.2$ (3)  $\delta = 0.5$ (4)  $\delta = 0.8$ (5)  $\delta = 1$ 

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $(1) \delta = 1$   $(2) \delta = 0.9$   $(3) \delta = 0.8$   $(4) \delta = 0.5$  $(5) \delta = 0.2$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint T<sub>i</sub> = 175 °C

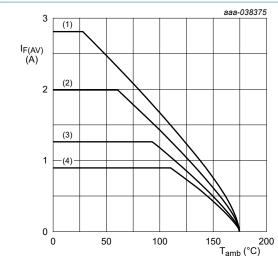
 $(1) \delta = 1$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta$  = 0.1; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $T_j = 175$  °C

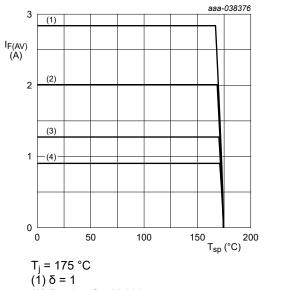
 $(1) \delta = 1$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

 $(4) \delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



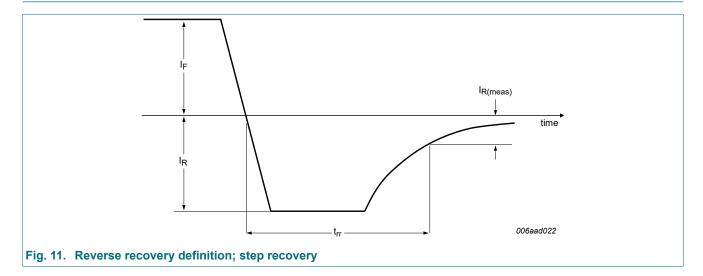
(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

 $(4) \delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

## 11. Test information



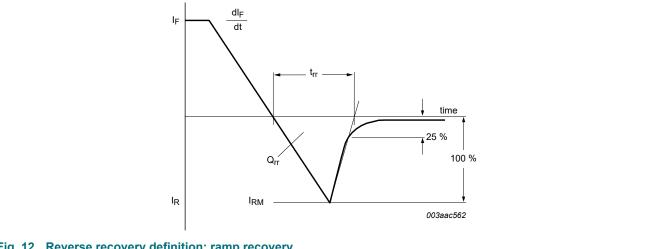


Fig. 12. Reverse recovery definition; ramp recovery

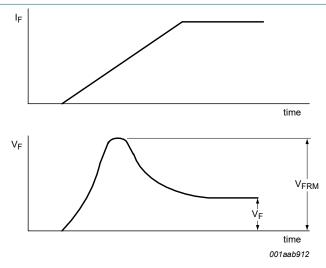


Fig. 13. Forward recovery definition

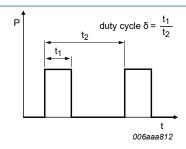


Fig. 14. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

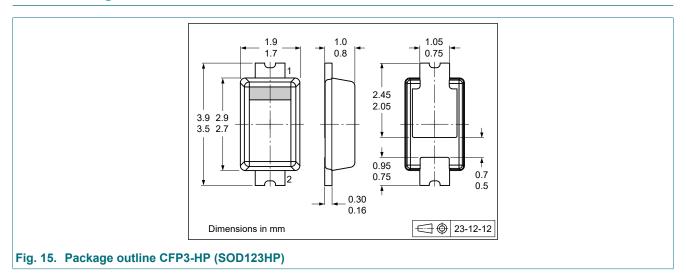
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_M \times \sqrt{\delta}$ 

with  $I_{\mbox{\scriptsize RMS}}$  defined as RMS current.

### **Quality information**

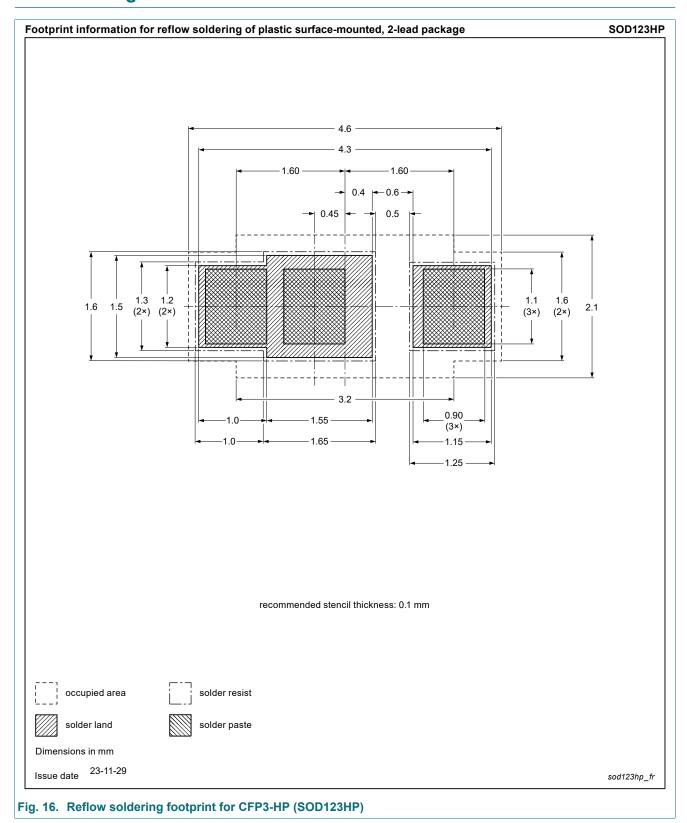
This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

# 12. Package outline



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# 13. Soldering



# 14. Revision history

### **Table 8. Revision history**

| Data sheet ID     | Release date | Data sheet status  | Change notice | Supersedes |
|-------------------|--------------|--------------------|---------------|------------|
| PMEG6020EXE-Q v.1 | 20240105     | Product data sheet | -             | -          |

## 15. Legal information

#### **Data sheet status**

| Document status [1][2]         | Product<br>status [3] | Definition  |
|--------------------------------|-----------------------|---|
| Objective [short] data sheet   | Development           | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification         | This document contains data from the preliminary specification.                       |
| Product [short]<br>data sheet  | Production            | This document contains the product specification.                                     |

- Please consult the most recently issued document before initiating or completing a design.
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